ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES®	Bannockbu	rn Illinois A	ll rights reserved un tions.	nder both	This docume level parts, t	ent is a declaration he declaration en	n of the substand compasses all lo	es within the manufactur wer level materials for w	er listed it hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form   http://www.ipc.org/IPC-175x Distribution				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information													
Company name* Company u			any unique ID			Unique ID Authority				Response Date*			
onsemi								2023-0			23-06-08		
ontact Name Title - Contact			et		Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro			viro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative			sentative	ntative I		Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Env			ct Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	MT9V124 CP	MT9V124EBKSTC- VGA 1/13 SOC CP			20			CP2		0.773	mg	Each	
Manufacturing Proccess Informatio	n												
Terminal Plating / Grid Array Mater	erminal Plating / Grid Array Material Terminal Base All		Alloy J	-STD-020 MSL	Rating	Peak Proces	s Body Tempera	ature Max Time at Peak	Temperat	ure Numbe	er of Reflow Cyc	eles	
SnAgCu CU Alloy		3	6		260	С	30	secon	ds 3				
Comments													
ATTENTION: MSL 3 Rated item requires B	ake and Dr	y Pack (after	electrical test)										
For more information regarding material cor	nposition p	lease refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.69	mg		Misc.	proprietary data		0.0064	mg
			Supplier	Silicon (Si)	7440-21-3		1.6668	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0167	mg
Die Attach	0.16	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.096	mg
			Supplier	Epoxy resins	129915-35-1		0.032	mg
			Supplier	Acrylic resins	Proprietary Data		0.032	mg
Electrode	0.17	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.1012	mg
			Supplier	Gold (Au)	7440-57-5		0.0041	mg
			Supplier	Copper (Cu)	7440-50-8		0.0025	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0621	mg
Glass Lid /Cap	7.89	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		1.1204	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.4815	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.6312	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.8679	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.789	mg
Lid Attach	0.003	mg		Photoinitiator	proprietary data		0.0008	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0022	mg
Solder Ball	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.0042	mg
			Supplier	Tin (Sn)	7440-31-5		0.1351	mg
			Supplier	Copper (Cu)	7440-50-8		0.0007	mg
Substrate and Solder Mask	0.72	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.072	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.342	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.306	mg